Filename: BILLOFMATERIALS_bom.xls

Date: 07/18/2012

PMP7177_RevB

COUNT	RefDes	Value	Description	Size	Part Number	MFR
1	C1	2.2uF	Capacitor, Ceramic Chip, 50V, X5R, 209	1206	Std	Std
1	C2	DNP	Capacitor, Ceramic Chip, 50V, X5R, 209	1206	Std	Std
1	C9	33nF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
1	C10	56pF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
1	C11	330pF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
1	C12	560uF	Capacitor, Electrolytic, Temp -55 to +1	8x7 mm	PCK0E561MCO	Nichicon
1	C14	10uF	Capacitor, Ceramic, X7R, 16V,10%	1206	C3216X7R1C10	TDK
1	C18	0.47uF	Capacitor, Ceramic Chip, 16V, ±10%	0603	STD	STD
1	C21	100nF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
1	C23	33pF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
1	C24	10uF	Capacitor, Ceramic Chip, 16V, ±10%	1206	STD	STD
1	C34	0.015uF	Capacitor, Ceramic Chip, 25V, ±10%	0603	STD	STD
2	C13 C15	0.1uF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
2	C16-17	4.7uF	Capacitor, Ceramic Chip, xxV, ±10%	1210	Std	STD
2	C22 C25	22uF	Capacitor, Ceramic Chip, xxV, ±10%	1206	STD	STD
3	C26-27 C30	DNP	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
2	C3 C6	1000pF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
2	C32 C29	4.7uF	Capacitor, Ceramic Chip, 10V, ±10%	0805	STD	STD
2	C36-37	1nF	Capacitor, Ceramic Chip, xxV, ±10%	0805	STD	STD
2	C4 C20	1uF	Capacitor, Ceramic Chip, 16V, ±10%	0603	STD	STD
2	C5 C19	0.047uF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
2	C7 C35	100pF	Capacitor, Ceramic Chip, xxV, ±10%	0603	STD	STD
4	C8 C28 C31 C33	1uF	Capacitor, Ceramic Chip, 25V, ±10%	0805	STD	STD
2	D1-2	MBR0540	Diode, Schottky, 0.5A, 20V	SOD-123	MBR0520L	Fairchild
5	J1 J4-7	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.	ED555/2DS	OST
1	L1	56uH	Inductor, SMT, yyA, zzmilliohm	0.402 x (MSS1038-xxxN	Coilcraft
1	L2	5.2uH	Inductor, SMT, yyA, zzmilliohm	0.402 x (MSS1038-xxxN	Coilcraft
2	L3-4	4.7uH	Inductor, SMT, yyA, zzmilliohm	0.118 x (LPS3015-472	Coilcraft
1	Q4	SQS484	MOSFET, NChan,	PWRPA	SQS484	Vishay

3	Q1-3	SQS464	MOSFET, NChan,	PWRPAK	SQS484	Vishay
1	R2	0.02	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Std
1	R3	66.5k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R8	0.1	Resistor, Chip, 1/16W, x%	0805	Std	Std
1	R9	69.8k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R13	6.65k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R16	24.9k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R20	47.5k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R27	21k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R28	44.2k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R29	33.2k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R30	8.06k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R32	14k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R34	665	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R37	6.98k	Resistor, Chip, 1/16W, x%	0603	Std	Std
1	R43	0	Resistor, Chip, 1/16W, x%	0805	Std	Std
9	R1 R4 R10-11 R14-15 R21 R23 R25	0	Resistor, Chip, 1/16W, x%	0603	Std	Std
4	R12 R6-7 R5	10	Resistor, Chip, 1/16W, x%	0603	Std	Std
2	R17 R22	DNP	Resistor, Chip, 1/16W, x%	0603	Std	Std
4	R18 R24 R36 R39	49.9	Resistor, Chip, 1/16W, x%	0603	Std	Std
3	R19 R26 R31	95.3k	Resistor, Chip, 1/16W, x%	0603	Std	Std
2	R33 R40	10k	Resistor, Chip, 1/16W, x%	0603	Std	Std
2	R35 R38	1.33k	Resistor, Chip, 1/16W, x%	0603	Std	Std
2	R41-42	1	Resistor, Metal Film, 1/4 watt, ± 5%	1206	Std	Std
5	TP11-12 TP14-16	TBD	Test Point, Red, Thru Hole Color Keyed	0.100 x (5000	Keystone
2	TP13 TP17	TBD	Test Point, Black, Thru Hole Color Key	0.100 x (5001	Keystone
6	TP1-3 TP5-7	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x (5000	Keystone
2	TP4 TP8	5001	Test Point, Black, Thru Hole Color Key	0.100 x (5001	Keystone
1	U1	LM25119PSQ	IC, Wide Input Range Dual Synchronou	QFN	LM25119PSQ	TI
1	U2	TPS62410DRC	IC, 2.25 MHz Dual Step Down Converte	QFN10	TPS62410DRC	TI
2	U3-4	TPS73201DBV	IC, Cap-Free NMOS 250-mA LDO Regul	SOT23-5	TPS732xxDBV	TI

Notes: 1. These assemblies are ESD sensitive, ESD precautions shall be observed.

2. These assemblies must be clean and free from flux and all contaminants.

Use of no clean flux is not acceptable.

- 3. These assemblies must comply with workmanship standards IPC-A-610 Class 2.
- 4. Ref designators marked with an asterisk ('**') cannot be substituted.

 All other components can be substituted with equivalent MFG's components.

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